

ABSTRACT OF THE DISCLOSURE

An integrated circuit device has an integrated circuit (2) formed on a front surface of a silicon substrate (1), an
5 insulating layer (12) formed on a rear surface of the substrate (1), and connection piles (4) penetrating the substrate (1), the integrated circuit (2), and the insulating layer (12).

An electronic device has plural integrated circuit devices (5a,5b) laminated in a multilayer structure, in which
10 a connection pile (4a) formed in an integrated circuit (2a) in the device (5a) as an upper position in the multilayer structure is electrically connected to a connection pile (4b) formed in an integrated circuit (2b) as a lower position under a requirement of an electric connection for the piles (4a,4b).
15 The pile (4a) is electrically insulated from the pile (4b) through the insulating layer (12) under no requirement of the electric connection for them.